## **Power MOSFET**

# 75 Amps, 60 Volts, N–Channel TO–220 and D<sup>2</sup>PAK

Designed for low voltage, high speed switching applications in power supplies, converters and power motor controls and bridge circuits.

#### Features

• Pb–Free Packages are Available

#### **Typical Applications**

- Power Supplies
- Converters
- Power Motor Controls
- Bridge Circuits

#### **MAXIMUM RATINGS** (T<sub>J</sub> = $25^{\circ}$ C unless otherwise noted)

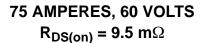
Rating	Symbol	Value	Unit					
Drain-to-Source Voltage	V <sub>DSS</sub>	60	Vdc					
Drain-to-Gate Voltage ( $R_{GS}$ = 10 M $\Omega$ )	V <sub>DGR</sub>	60	Vdc					
Gate–to–Source Voltage – Continuous – Non–Repetitive (t <sub>p</sub> ≤10 ms)	V <sub>GS</sub> V <sub>GS</sub>	±20 ±30	Vdc					
Drain Current – Continuous @ $T_A = 25^{\circ}C$ – Continuous @ $T_A = 100^{\circ}C$ – Single Pulse ( $t_p \le 10 \ \mu s$ )	I <sub>D</sub> I <sub>D</sub> I <sub>DM</sub>	75 50 225	Adc Apk					
Total Power Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C Total Power Dissipation @ T <sub>A</sub> = 25°C	P <sub>D</sub>	214 1.4 2.4	W W/°C W					
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	–55 to +175	°C					
$            Single Pulse Drain-to-Source Avalanche \\             Energy - Starting T_J = 25^\circ C \\              (V_{DD} = 50 \ Vdc, \ V_{GS} = 10 \ Vdc, \ L = 0.3 \ mH \\             I_{L(pk)} = 75 \ A, \ V_{DS} = 60 \ Vdc) $	E <sub>AS</sub>	844	mJ					
Thermal Resistance – Junction–to–Case – Junction–to–Ambient	$R_{ heta JC} \ R_{ heta JA}$	0.7 62.5	°C/W					
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	ΤL	260	°C					

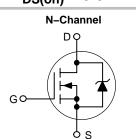
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

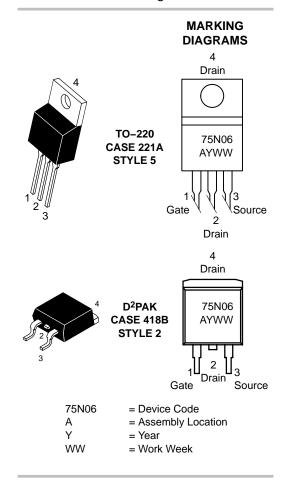


#### ON Semiconductor<sup>®</sup>

http://onsemi.com







#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

#### 5N06

t<sub>f</sub>

 $\mathsf{Q}_\mathsf{T}$ 

Symbol	Min	Turn	Max	Unit
Symbol	IVIIII	Тур	IVIAX	Unit
V <sub>(BR)DSS</sub>	60	71	_	Vdc
	-	73	-	mV/°C
I <sub>DSS</sub>	-	- -	10 100	μAdc
I <sub>GSS</sub>	I	-	±100	nAdc
V <sub>GS(th)</sub>	2.0	2.8	4.0	Vdc
	-	8.0	-	mV/°C
R <sub>DS(on)</sub>	-	8.2	9.5	mΩ
V <sub>DS(on)</sub>	-	0.72 0.63	0.86 -	Vdc
9 <sub>FS</sub>	-	40.2	-	mhos
		•	•	
C <sub>iss</sub>	-	3220	4510	pF
C <sub>oss</sub>	-	1020	1430	1
C <sub>rss</sub>	-	234	330	
t <sub>d(on)</sub>	-	16	25	ns
t <sub>r</sub>	-	112	155	
t <sub>d(off)</sub>	-	90	125	

100

92

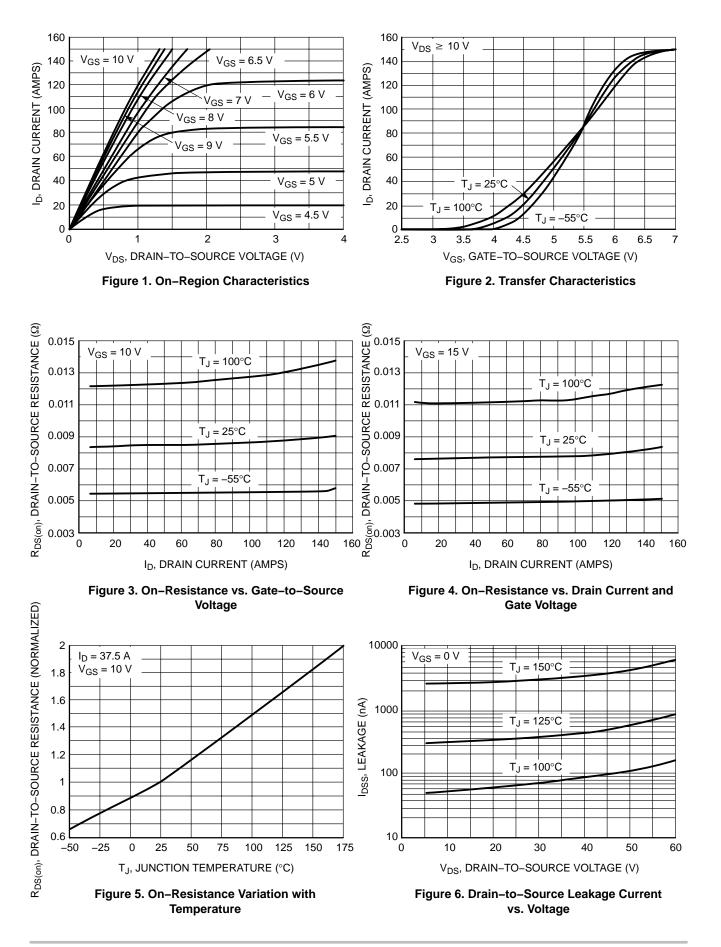
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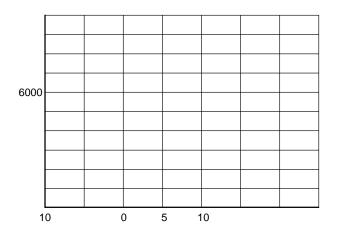
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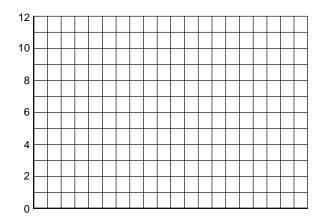
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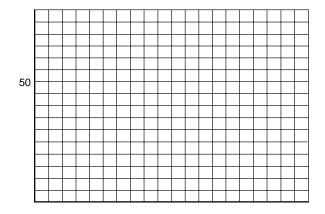
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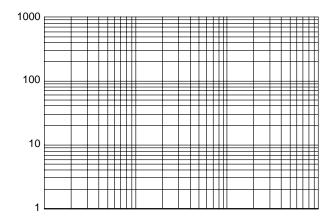


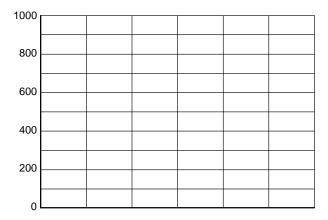




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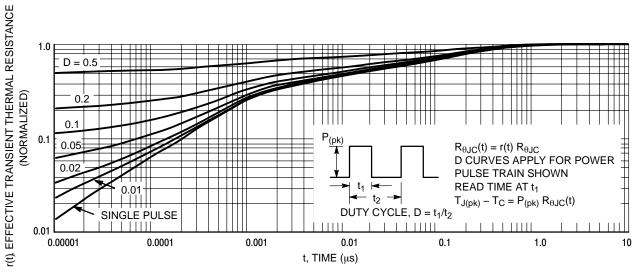


Figure 13. Thermal Response

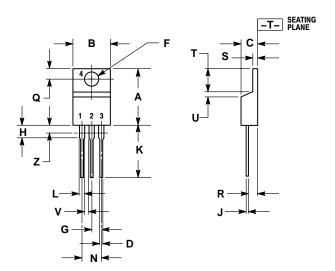
#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NTP75N06	TO-220	50 Units/Rail
NTP75N06G	TO-220 (Pb-Free)	50 Units/Rail
NTB75N06	D <sup>2</sup> PAK	50 Units/Rail
NTB75N06G	D <sup>2</sup> PAK (Pb-Free)	50 Units/Rail
NTB75N06T4	D <sup>2</sup> PAK	800 Tape & Reel
NTB75N06T4G	D <sup>2</sup> PAK (Pb–Free)	800 Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

TO-220 CASE 221A-09 **ISSUE AA** 



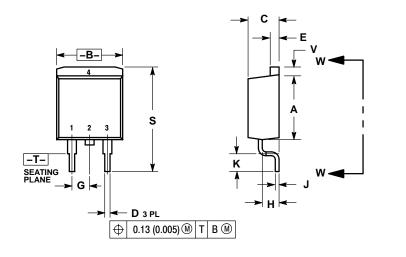
NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INC	HES	MILLIMETER			
DIM	MIN	MAX	MIN	MAX		
Α	0.570	0.620	14.48	15.75		
В	0.380	0.405	9.66	10.28		
С	0.160	0.190	4.07	4.82		
D	0.025	0.035	0.64	0.88		
F	0.142	0.147	3.61	3.73		
G	0.095	0.105	2.42	2.66		
Н	0.110	0.155	2.80	3.93		
ſ	0.018	0.025	0.46	0.64		
Κ	0.500	0.562	12.70	14.27		
L	0.045	0.060	1.15	1.52		
Ν	0.190	0.210	4.83	5.33		
Q	0.100	0.120	2.54	3.04		
R	0.080	0.110	2.04	2.79		
S	0.045	0.055	1.15	1.39		
Т	0.235	0.255	5.97	6.47		
U	0.000	0.050	0.00	1.27		
V	0.045		1.15			
Ζ		0.080		2.04		

STYLE 5: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN

#### PACKAGE DIMENSIONS

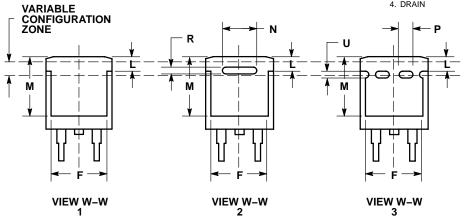
D<sup>2</sup>PAK CASE 418B-04 **ISSUE J** 



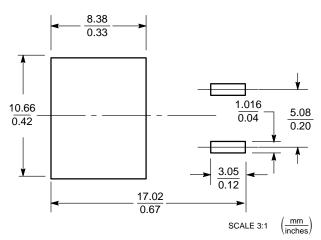
NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

	INC	HES	MILLIM	IETERS	
DIM	MIN	MIN MAX MIN			
Α	0.340	0.380	8.64	9.65	
В	0.380	0.405	9.65	10.29	
С	0.160	0.190	4.06	4.83	
D	0.020	0.035	0.51	0.89	
Е	0.045	0.055	1.14	1.40	
F	0.310	0.350	7.87	8.89	
G	0.100	BSC	2.54 BSC		
Н	0.080	0.110	2.03	2.79	
J	0.018	0.025	0.46	0.64	
κ	0.090	0.110	2.29	2.79	
L	0.052	0.072	1.32	1.83	
М	0.280 0.320		7.11	8.13	
Ν	0.197	REF	5.00	REF	
Ρ	0.079	.079 REF 2.00 RI		REF	
R	0.039 REF		0.99	REF	
S	0.575	0.625	14.60	15.88	
V	0.045	0.055	1.14	1.40	

STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4 DRAIN



#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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